



Scalability of CO₂ amplifiers to generate stable > 500W extreme ultraviolet (EUV) beams

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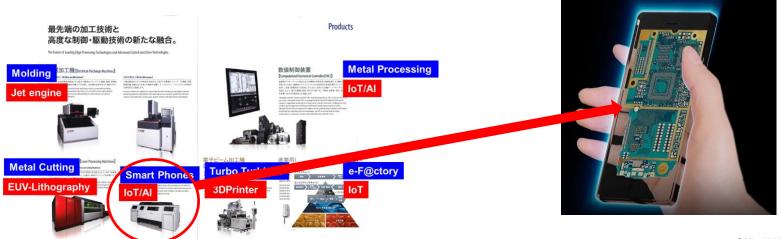
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- 1. We are supplying advanced machines for fast-growing market such as smart phones.
- 2. Today IoT/AI market is emerging and we are preparing for the new demands.







Introduction

- 1. Why we need EUVL for IoT/AI era
- 2. Our progress for EUVL success
- 3. Toward > 500W EUV beams

Summary

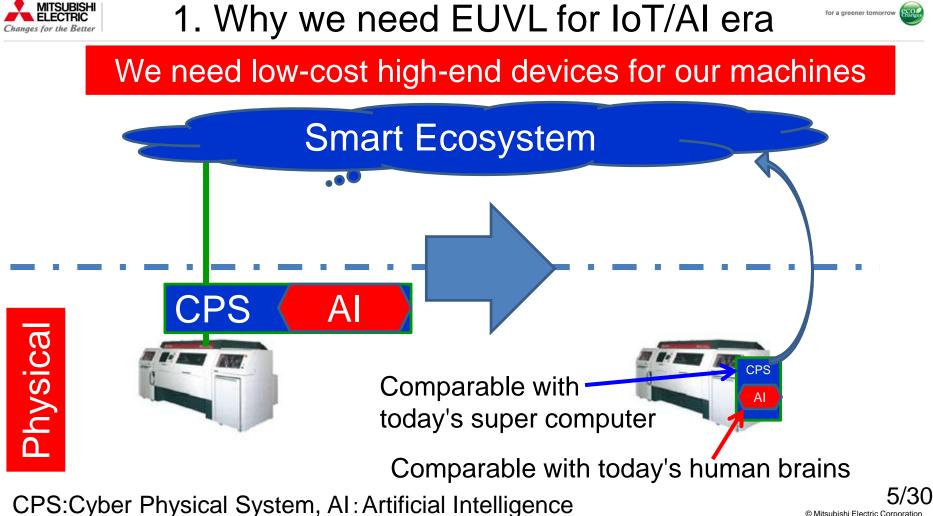






1. Why we need EUVL for IoT/AI era





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JAPANESE-GERMAN CENTER BERLIN [JDZB] MERCATOR INSTITUTE FOR CHINA STUDIES [MERICS] in cooperation with COLOGNE INSTITUTE FOR ECONOMIC RESEARCH [IW] FUJITSU RESEARCH INSTITUTE [FRI]

TENTATIVE PROGRAMME

for the experts' symposium The Future of Manufacturing: Industry 4.0 in China, Germany and Japan

on Monday, June 12, 2017 at the JDZB, Saargemuender Str. 2, 14195 Berlin

http://www.jdzb.de/en/events/single-view/id/1632/

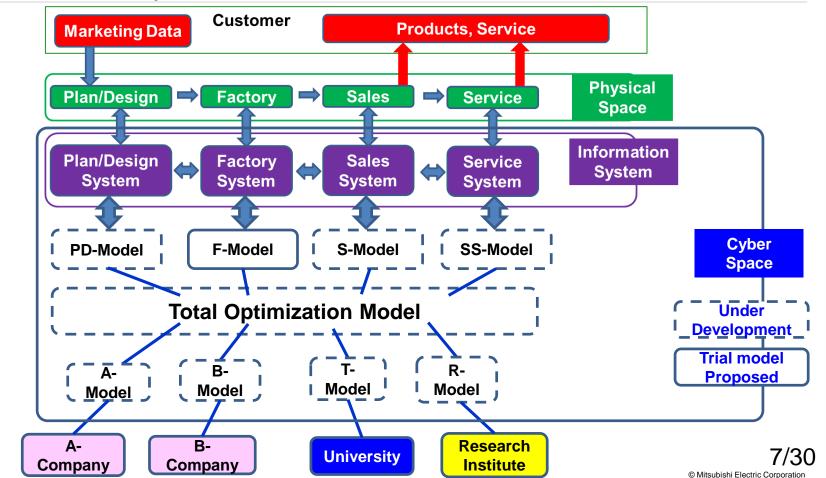


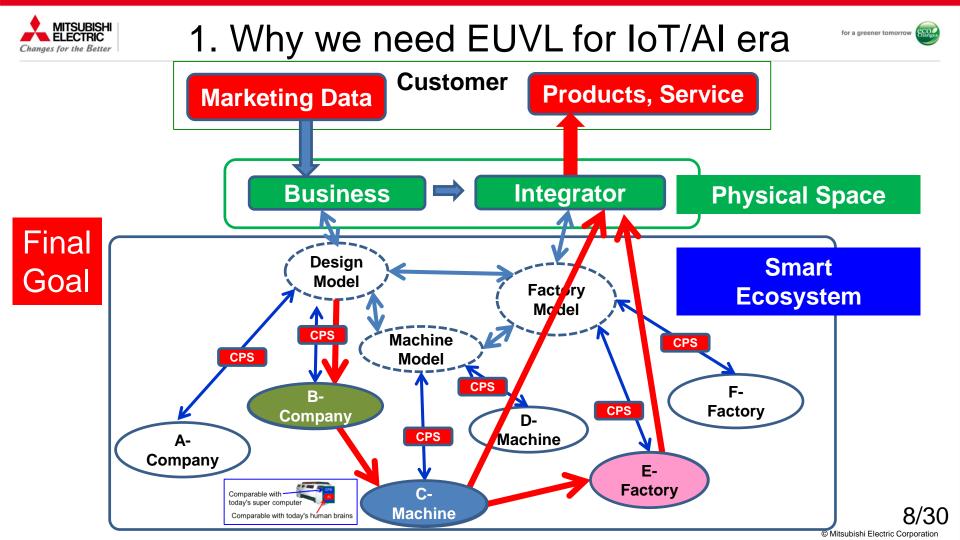
Middle

Goal

1. Why we need EUVL for IoT/AI era





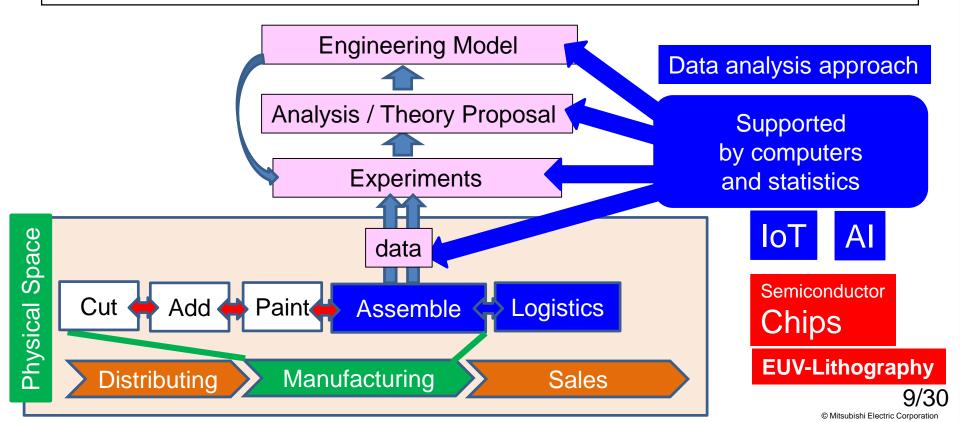






for a greener tomorrow

Modeling requires advanced theories and calculation powers



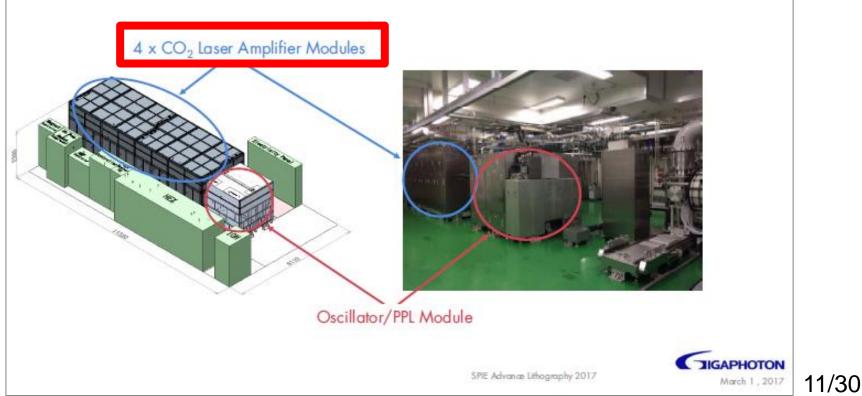






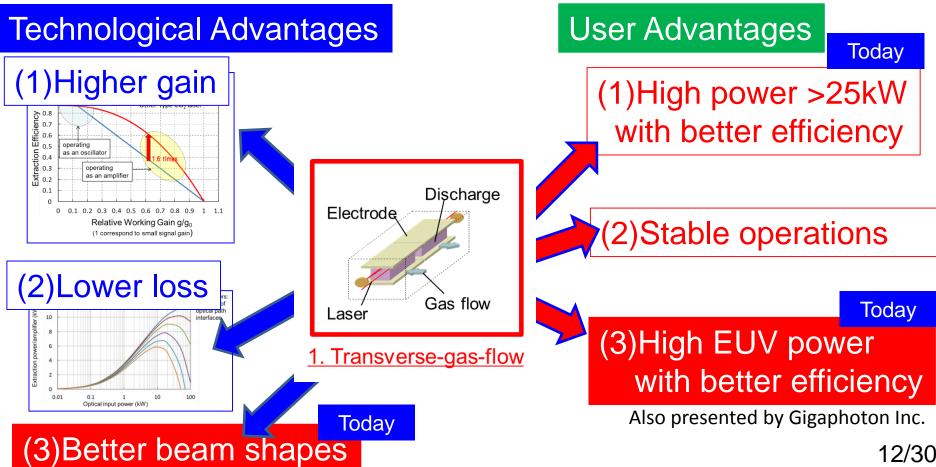


Pilot System Driver Laser and PPL System



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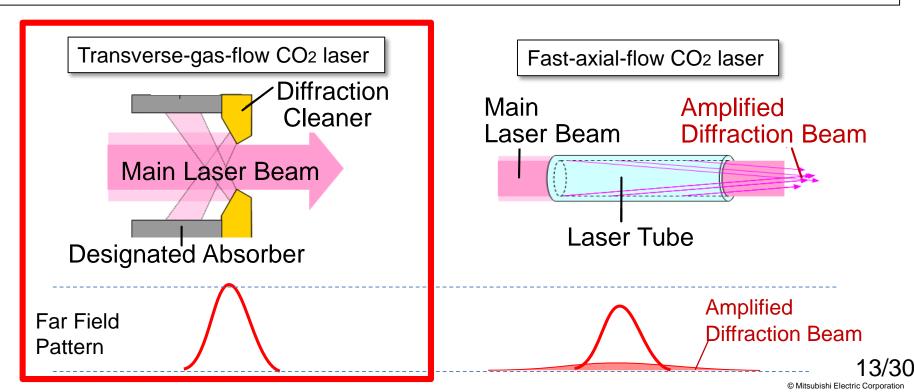


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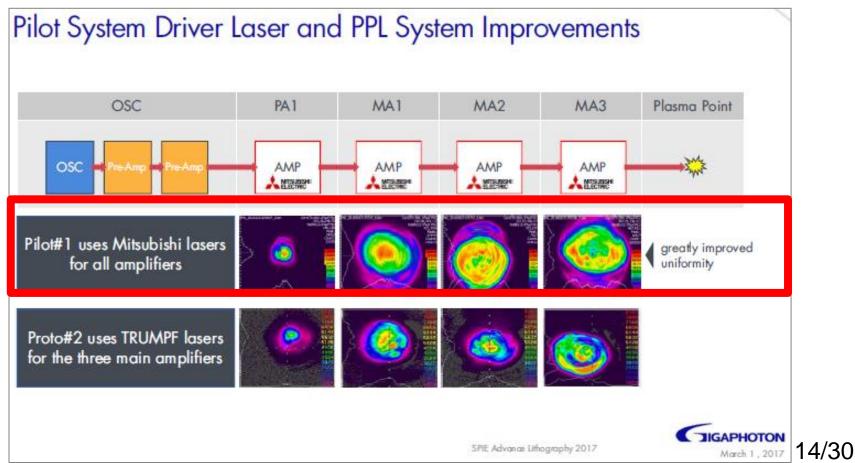
Better beam shapes improved for fine metal cutting applications are also effective for efficient EUV generation





2. Our roll for EUVL success





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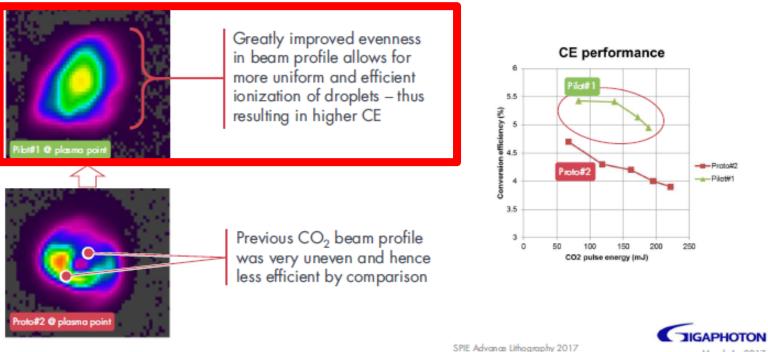


2. Our roll for EUVL success



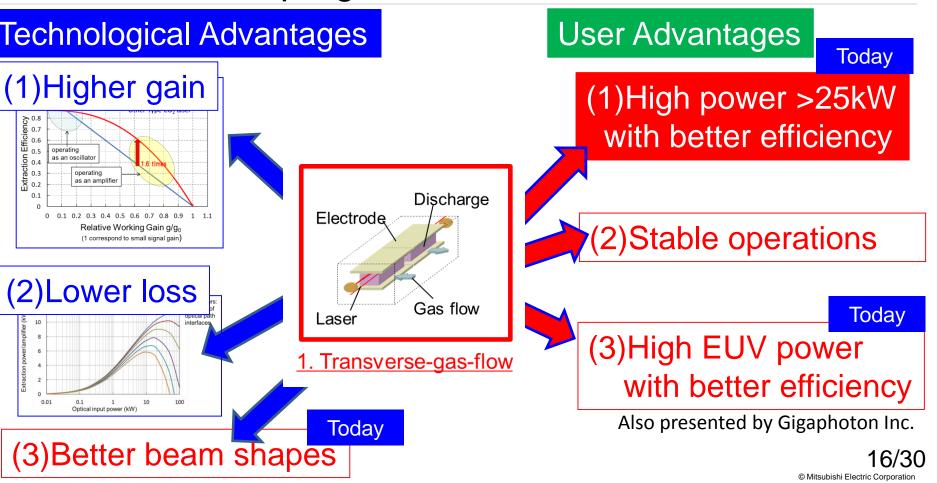
Pilot System Driver Laser and PPL System

>5% CE was achieved due to the greatly improved CO₂ beam profile



















High Power EUV Source for High NA EUV exposure tool

EUV ave.Power[W] Conversion Efficiency [%]										Lithography	R(nm)*	NA	۶/n (nm)	Power (W)	
	@100kHz			2%	3%	4%	5%	6%	7%	8%	KrF dry	102	0.85	248	40
[m]	15		1.5		0.0	0.0	0.0	0.0	0.0	0.0	ArF dry	73	0.93	193	45
	50	[5	19.1	28.7	38.2	47.8	57.3	66.9	76.4	F ₂ dry	69		157	
	100	- [10	46.4	69.6	92.8	i.0	139.2	162.4	185.6	ArF immersion EUV EUV (High NA)				
	150	[15	73.7	110.6	147.4	3	221.1	258.0	294.8		50	1.35	134	90
	200		20	101.0	15	202.0	5	303.0	353.5	404.0		14	0.33	13.5	>250
	250	Σ	25	128.3	192.5	256.6	320.8	384.9	449.1	513.2		7	0.6	13.5	>500
	300	2	30		233.4	31.2	389.0	466.8	544.6	622.4					
5	350	5	35	182.9	274.4	365.8	457.3	548.7	640.2	731.6			-		
CO2 laser Energy	400	8	40	210.2	315.3	420.4	525.5	630.6	735.7	840.8				100	
	450	•	45	237.5	356.3	475.0	593,8	712.5	831.3	950.0				➡ E	÷.
	500	2	50		397.2	529.6	662.0	794.4	926.8	1059.2		LIV/	41	10/002	HVM3
	550	Ĩ.	55		438.2	584.2	730.3	876.3	1022.4	1168.4		HVM1	W1	HVM2	
	600	ŝ	60		479.1	638.8	798.5	958.2	1117.9	1277.6		0.50	147	20014	50014
	650	8	65	346.7	520.1	693.4	866.8	1040.1	1213.5	1386.8	EUV Power	250	VVV	300W	500W
	700	ö	70		561.0	748.0	935.0	1122.0	1309.0	1496.0	Dulas Data	1.001		1001.11	1001.0
	750	- H	75		602.0	802.6	1003.3	1203.9	1404.6	1605.2	Pulse Rate	100	KHZ	100kHz	100kH
	800	ŀ	80		642.9	857.2	1071.5	1285.8	1500.1	1714.4	CE	4.5%	~		
	850 900	ŀ	85 90		683.9 724.8	911.8 966.4	1139.8 1208.0	1367.7 1449.6	1595.7 1691.2	1823.6 1932.8			0%	5%	5%
	950	ŀ	90		765.8	1021.0	1208.0	1531.5	1786.8	2042.0	CO ₂ Laser Power				
	1000	ŀ	100	537.8	806.7	1021.0	1344.5	1613.4	1882.3	2151.2		r 25k	W	25kW	40kW
_	1000		100	007.0	000.1	1070.0	1011.0	1010.4	1002.0	2101.2					

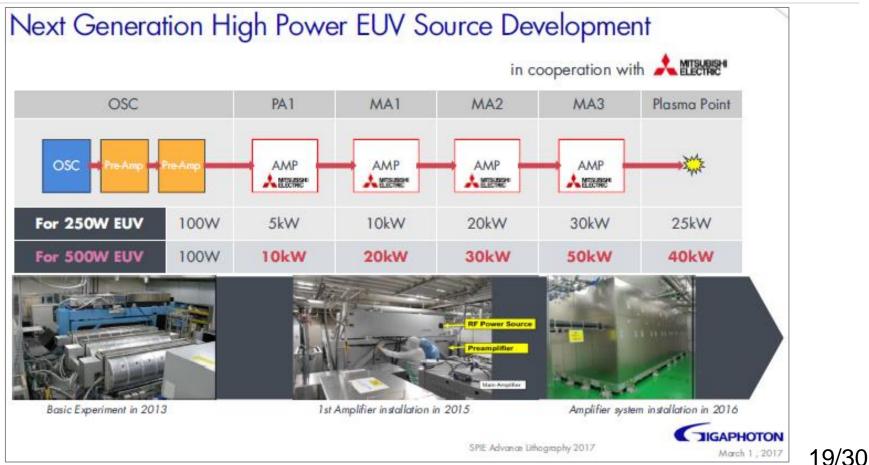
SPIE Advance Lithography 2017



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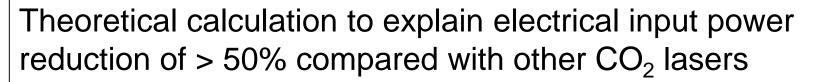
Possible technological bottlenecks toward higher power generation and prospects.

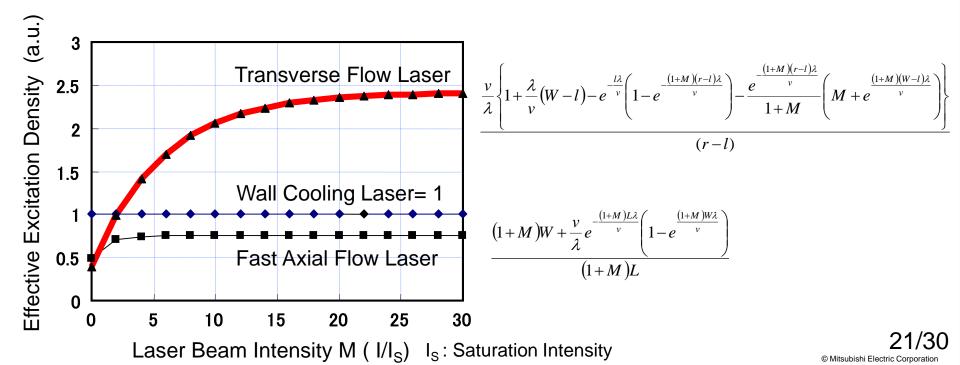
1. Beam shape degradation — Within our estimation

2. Higher electric powers













Possible technological bottlenecks toward higher power generation and prospects.

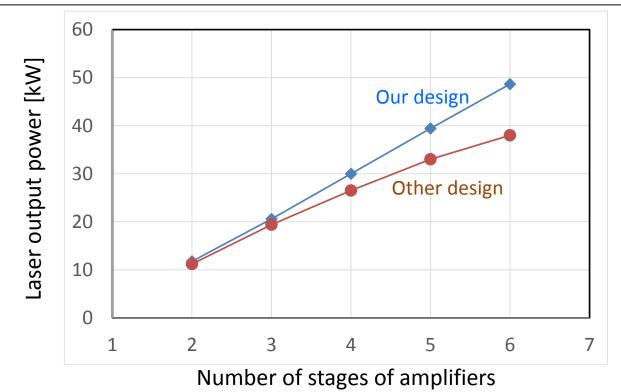
1. Beam shape degradation — Within our estimation

- 2. Higher electric powers > Within conventional powers even at 40kW
- 3. Extraction degradation





Scalable amplification system by increasing the number of stages of amplifiers can be easily configured

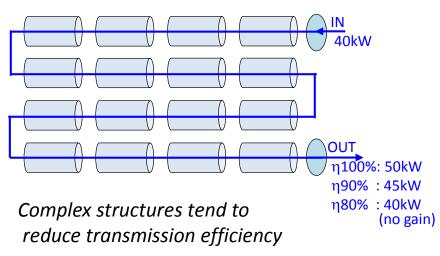


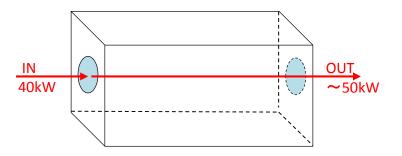




Higher optical transmission efficiency is the essential property for high-power amplifiers

High-power amplifier (assuming power extraction ability of 10kW)



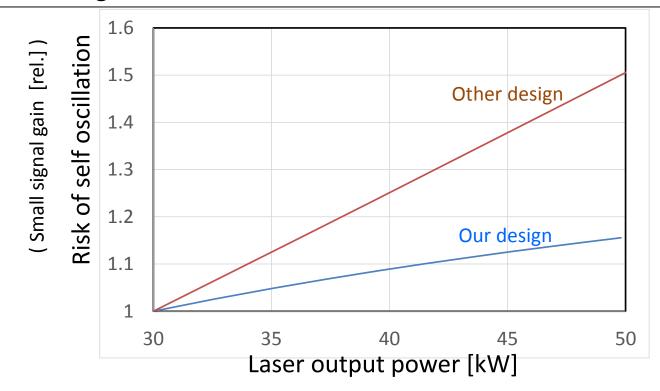


The ultimately simple structure of our amplifier allows for the highest transmission efficiency and lead to scalable amplifier system





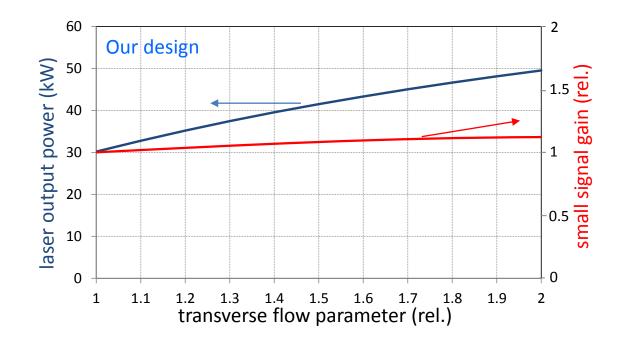
The output power can be increased without significantly increasing the risk of self-oscillation







The output power can be increased without significantly increasing the risk of self-oscillation









Possible technological bottlenecks toward higher power generation and prospects.

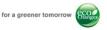
1. Beam shape degradation — Within our estimation

- 2. Higher electric powers > Within conventional powers even at 40kW
- 3. Extraction degradation > Within our estimation





Summary



- Scalability of CO₂ amplifiers to generate > 500W EUV beams that are required in the near future for high-volume-manufacturing of IoT/AI devices are discussed.
- 2. We consider that with the emerging application fields related to IoT/AI technology, EUV lithography has become essential technology.
- 3. We have shown that CO_2 amplifiers with transverse-gas-flow configuration could solve technological bottlenecks to enhance the EUV powers more than 500W.







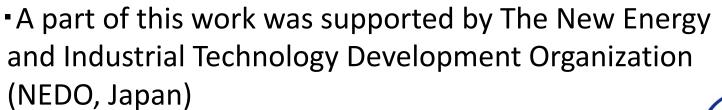


Digital pre-pulsing technology based on controllable digital picosecond lasers are also going to be proposed in the near future for better EUV efficiency.





 The experiments were performed by research members of Mitsubishi Electric corp. and Gigaphoton Inc.









Thank you very much for your attention

